

Application Number 10/730,878

Response to final Office Action mailed August 3, 2007

### **AMENDMENTS TO THE SPECIFICATION**

Please replace paragraph [0051] of the originally-filed disclosure with the following amended paragraph:

[0051] FIGS. 6A-6B are schematic diagrams illustrating an example embodiment of a multi-module IMD 601 having multiple interconnect sites according to the present invention. FIG. 6A shows a distributed IMD have multiple lead connection modules 613 that are located adjacent to each other while being near a control module 610. In contrast, FIG. 6B shows a distributed IMD have multiple lead connection modules 613 that are located on opposite sides of the control module 610. In FIGS. 6A and 6B, lead connection modules are included in overmold 622. The lead connection modules 613 provide a mechanism for electrically connecting electronics within control module 610 to one or more external leads 643. As shown in FIGS. 6A-6B, external leads 643 may be separable from IMD 601. In this manner, lead connection modules 613 may be configured to accept external leads 643. The external leads provide an electrical signal path from a desired part of the patient's body to IMD 601.